METHOD OF PROTECTING BOND WIRES DURING MOLDING AND HANDLING

ABSTRACT OF THE DISCLOSURE

A method of making a semiconductor device and the device wherein a chip is provided having plural bond pads thereon. A plurality of adjacent wires is provided, each wire having one end thereof coupled to and extending from one of the bond pads. The other end of each wire is coupled to one of a plurality of lead fingers. A mass of hardenable, flowable adhesive having a viscosity in its flowable state sufficient to enable the adhesive to rest on a the wire until hardened, preferably an epoxy, is disposed on adjacent wires and the adhesive is then hardened. Optionally, some of the adhesive is permitted to be disposed on a surface of the chip and beneath a wire and then hardened.

FIGURE 4

This Sheet Has Been Replaced

